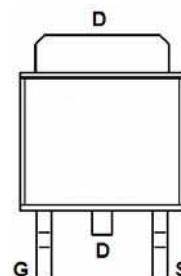
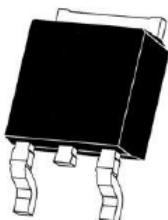
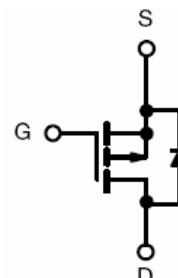


**-40V(D-S) P-Channel Enhancement Mode Power MOS FET****General Features**

- $V_{DS} = -40V, I_D = -70A$
- $R_{DS(ON)} < 10m\Omega @ V_{GS} = -10V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

**Lead Free****Marking and pin assignment****TO-252-2L top view****Schematic diagram****Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MSP0370D	MSP0370D	TO-252-2L	-	-	-

**Absolute Maximum Ratings ( $T_C=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-70	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	-49.5	A
Pulsed Drain Current	$I_{DM}$	-200	A
Maximum Power Dissipation	$P_D$	130	W
Derating factor		1.04	W/ $^\circ C$
Single pulse avalanche energy <small>(Note 5)</small>	$E_{AS}$	1012	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

**Thermal Characteristic**

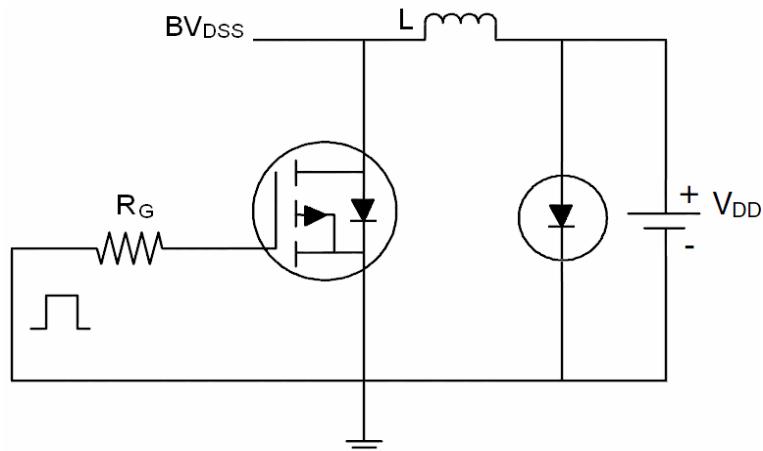
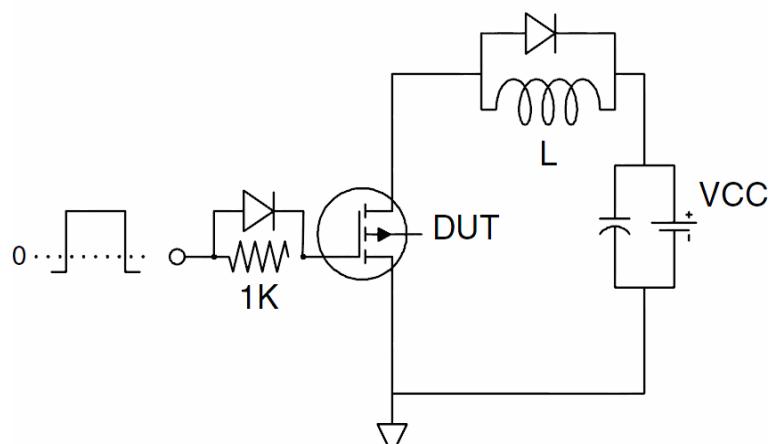
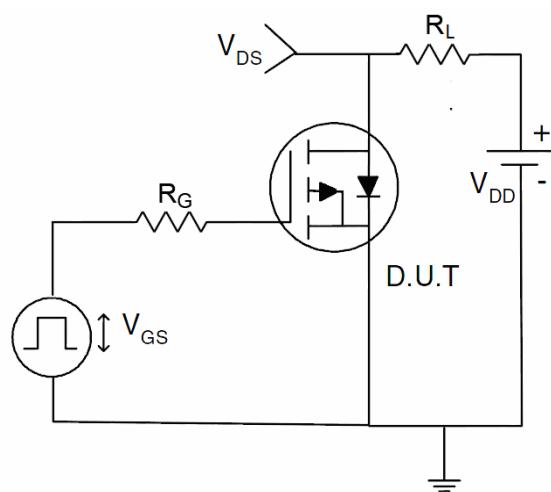
Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	0.96	°C/W
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**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

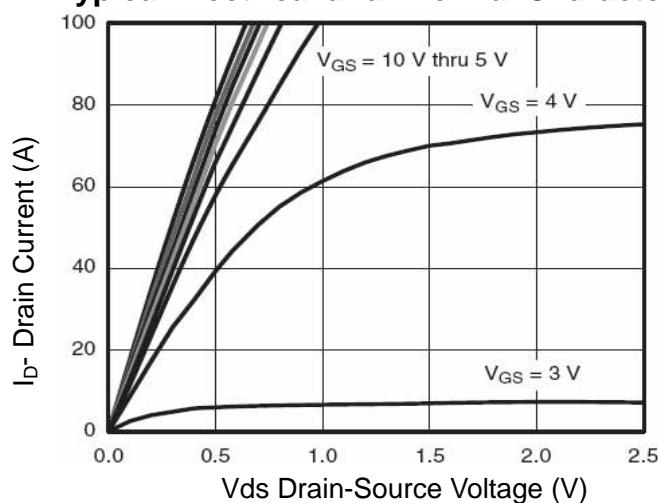
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.2	-1.9	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	7.5	10	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-20A	-	50	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, F=1.0MHz	-	5380	-	PF
Output Capacitance	C <sub>oss</sub>		-	570	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	500	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-20V, R <sub>L</sub> =2Ω, V <sub>GS</sub> =-10V, R <sub>G</sub> =1Ω	-	15	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	12	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	70	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	18	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-20, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	-	106	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	22	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	27	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-70A	-		-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	-70	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF = - 70A di/dt = -100A/μs <sup>(Note 3)</sup>	-	53	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	50	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

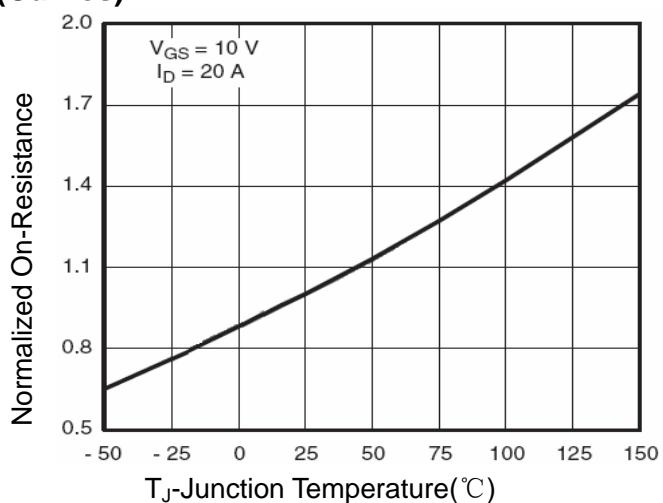
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition: T<sub>j</sub>=25°C, V<sub>DD</sub>=-20V, V<sub>G</sub>=-10V, L=1mH, R<sub>g</sub>=25Ω, I<sub>AS</sub>=45A

**Test Circuit****1) E<sub>AS</sub> Test Circuit****2) Gate Charge Test Circuit****3) Switch Time Test Circuit**

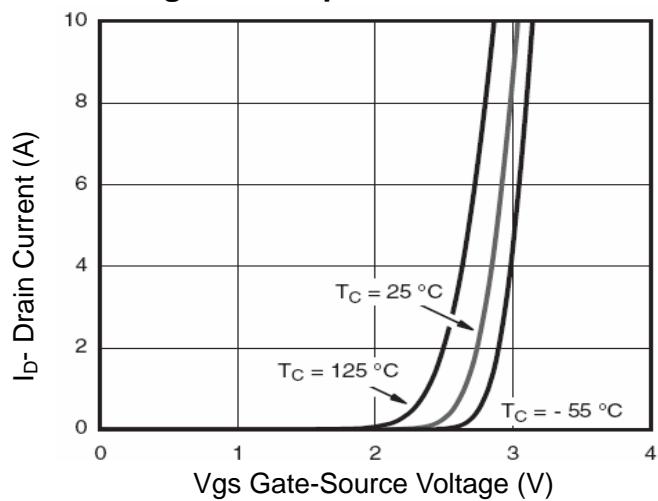
### Typical Electrical and Thermal Characteristics (Curves)



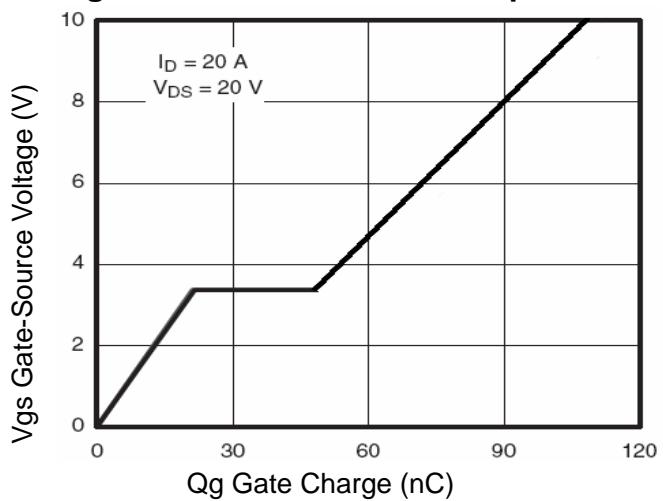
**Figure 1 Output Characteristics**



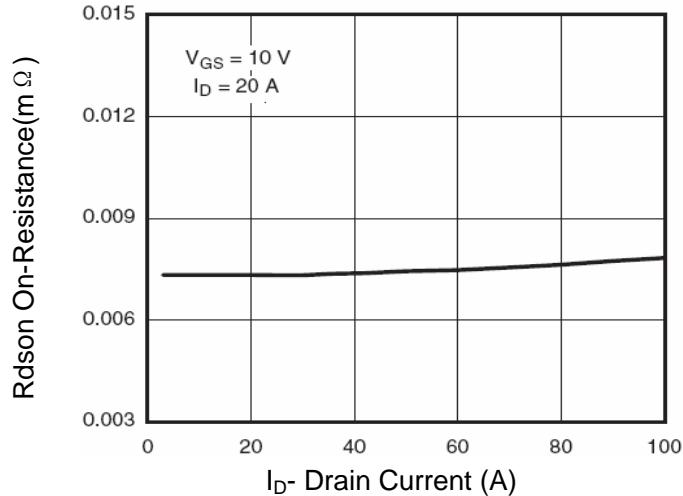
**Figure 4 Rdson-Junction Temperature**



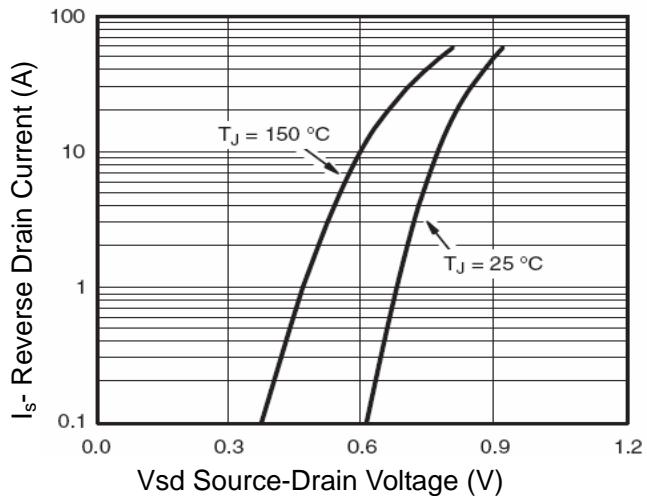
**Figure 2 Transfer Characteristics**



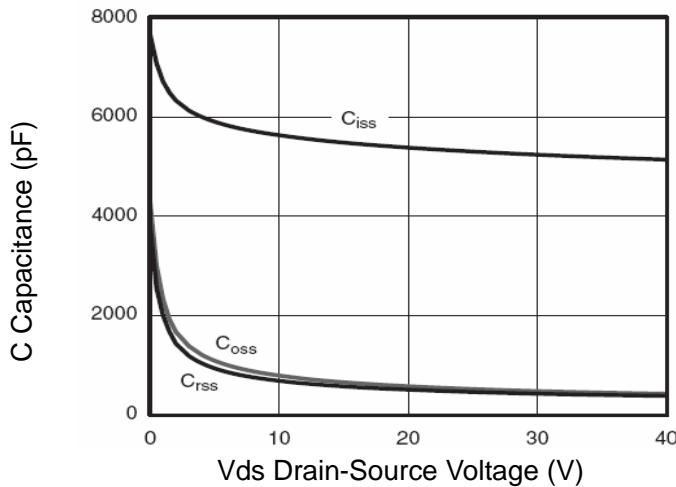
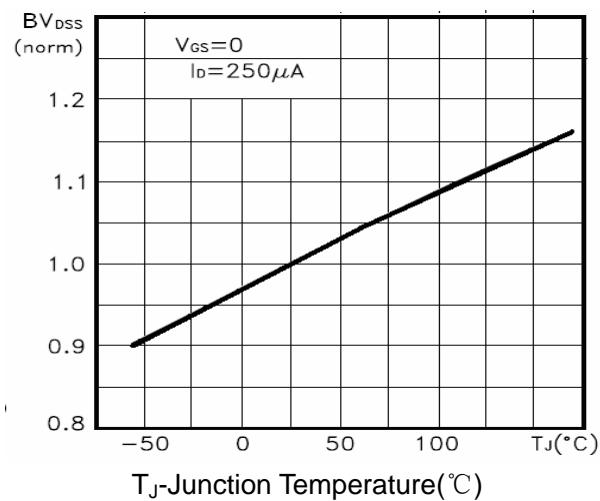
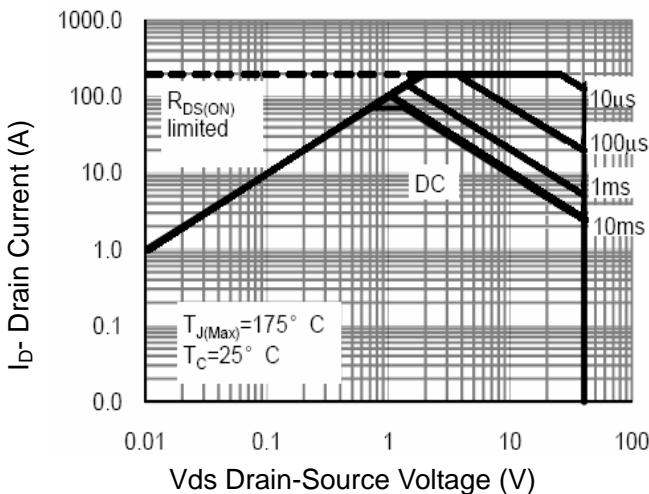
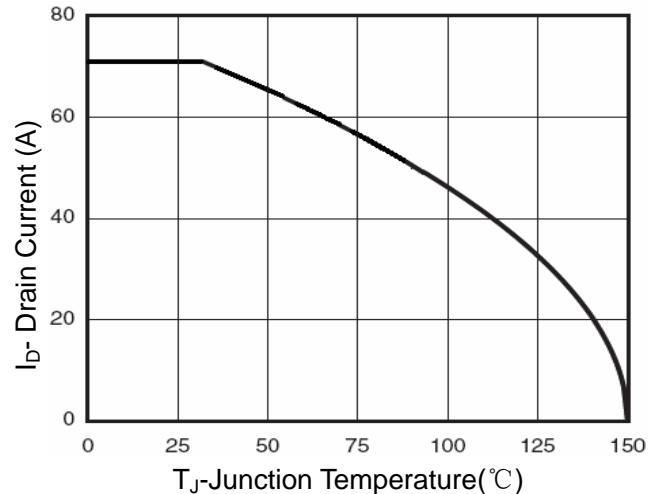
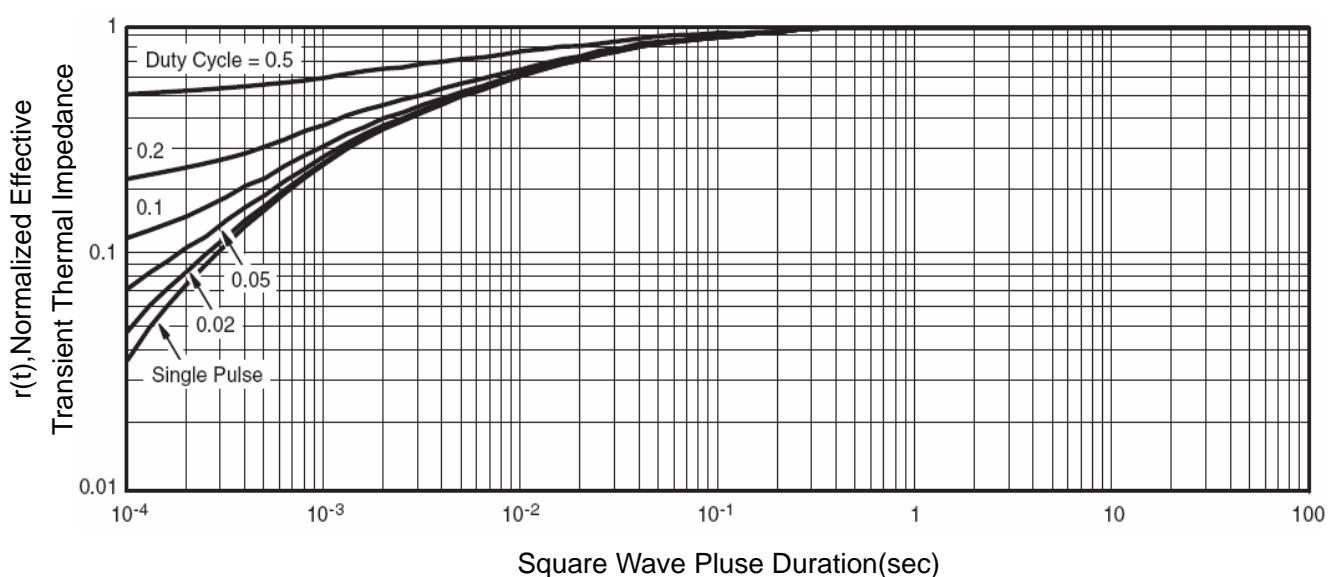
**Figure 5 Gate Charge**



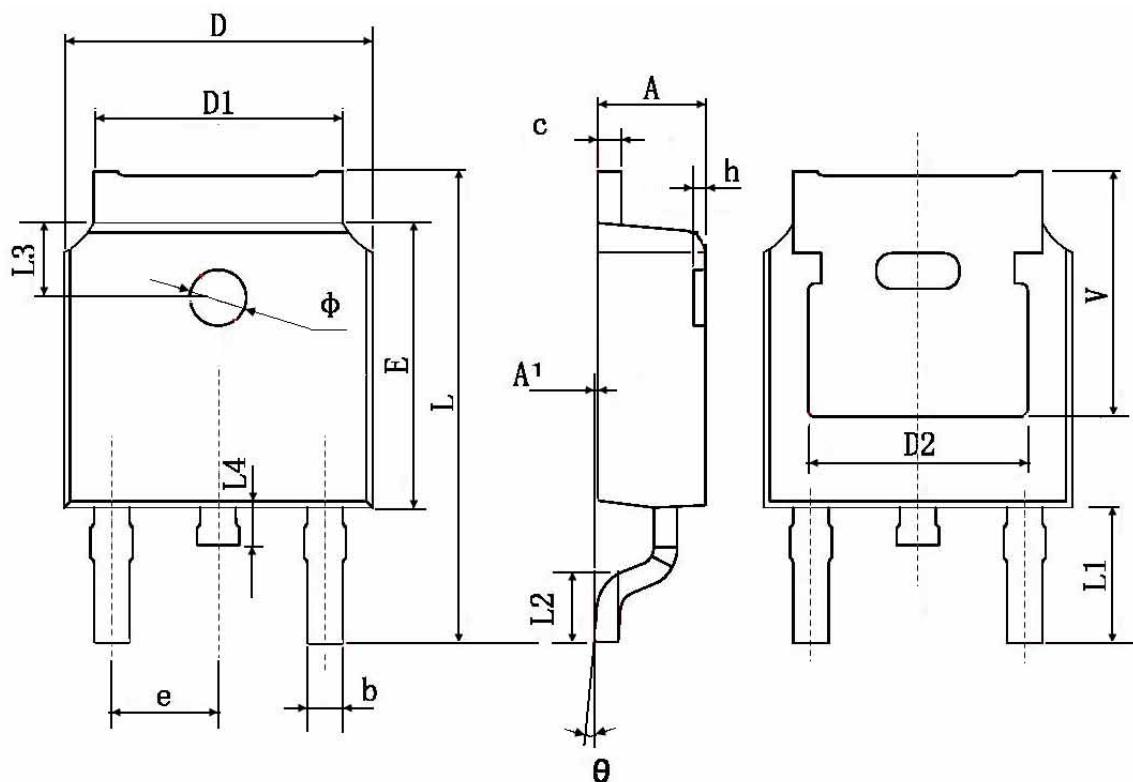
**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9  $BV_{DSS}$  vs Junction Temperature****Figure 8 Safe Operation Area****Figure 10  $I_D$  Current Derating vs Junction Temperature****Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	